

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- LED lighting
- Telecom
- Adapter
- Sever
- Solar/UPS

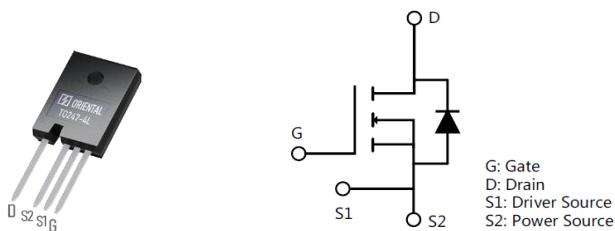
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	650	V
I_D , pulse	336	A
$R_{DS(ON)}$, max @ $V_{GS}=10V$	19	mΩ
Q_g	193	nC
PD	680	W

Marking Information

Product Name	Package	Marking
OSG65R019H4T3ZF	TO247-4L	OSG65R019H4T3Z

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	650	V
Gate-source voltage (static)	V_{GS}	± 20	V
Gate-source voltage (dynamic)		± 30	V
Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$	I_D	112	A
Continuous drain current ¹⁾ , $T_c=100^\circ\text{C}$		70.8	
Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$	$I_{D, \text{pulse}}$	336	A
Continuous diode forward current ¹⁾ , $T_c=25^\circ\text{C}$	I_S	112	A
Diode pulsed current ²⁾ , $T_c=25^\circ\text{C}$	$I_{S, \text{pulse}}$	336	A
Power dissipation ³⁾ , $T_c=25^\circ\text{C}$	P_D	680	W
Single pulsed avalanche energy ⁴⁾	E_{AS}	2250	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 400\text{ V}$	dv/dt	100	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 400\text{ V}$, $I_{SD} \leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.18	$^\circ\text{C/W}$
Thermal resistance, junction-ambient	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	650			V	$V_{GS}=0\text{ V}$, $I_D=2\text{ mA}$
Gate threshold voltage	$V_{GS(\text{th})}$	3.5		5.5	V	$V_{DS}=V_{GS}$, $I_D=2\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		16	19	$\text{m}\Omega$	$V_{GS}=10\text{ V}$, $I_D=57\text{ A}$
			42			$V_{GS}=10\text{ V}$, $I_D=57\text{ A}$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GS}			100	nA	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	I_{DS}			10	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$
Gate resistance	R_G		1.3		Ω	$f=1\text{ MHz}$, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		10620		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		587		pF	
Reverse transfer capacitance	C _{rss}		5.2		pF	
Effective output capacitance, energy related	C _{o(er)}		381		pF	
Effective output capacitance, time related	C _{o(tr)}		2390		pF	V _{GS} =0 V, V _{DS} =0 V-400 V
Turn-on delay time	t _{d(on)}		45		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =55 A
Rise time	t _r		49		ns	
Turn-off delay time	t _{d(off)}		82.4		ns	
Fall time	t _f		2.3		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		193		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =55 A
Gate-source charge	Q _{gs}		71		nC	
Gate-drain charge	Q _{gd}		66		nC	
Gate plateau voltage	V _{plateau}		7.2		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =112 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		214		ns	V _R =400 V, I _S =55 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		1.6		μC	
Peak reverse recovery current	I _{rrm}		12.5		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V_{DD}=100 V, V_{GS}=10 V, L=80 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

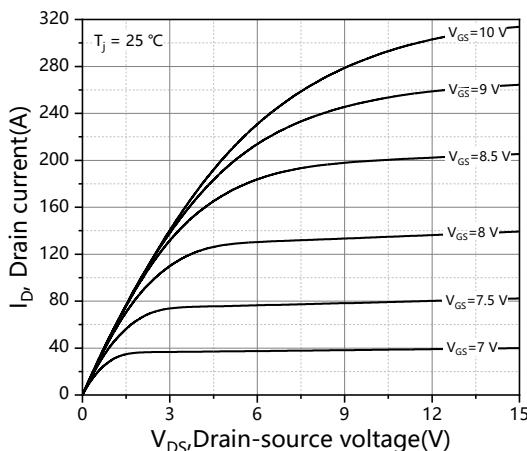


Figure 1. Typ. output characteristics $T_j=25^\circ\text{C}$

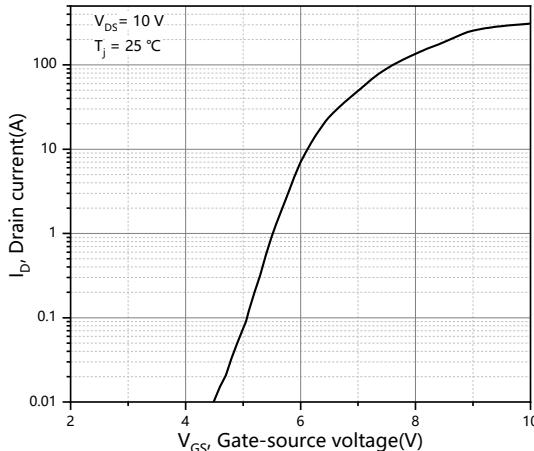


Figure 2. Typ. transfer characteristics

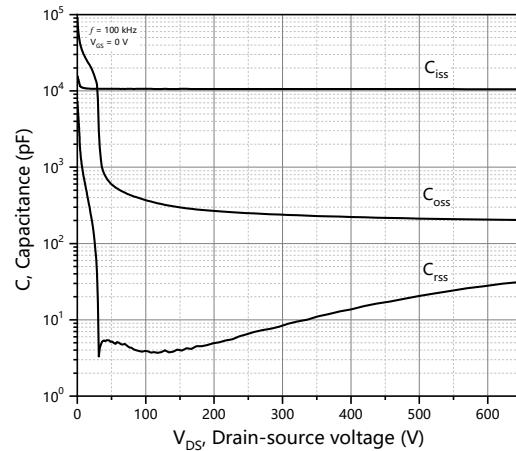


Figure 3. Typ. capacitances

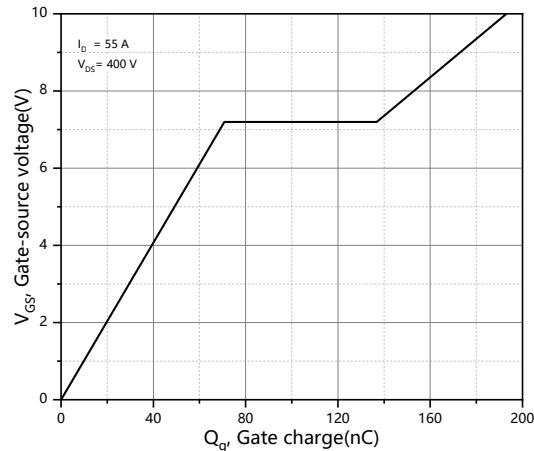


Figure 4. Typ. gate charge

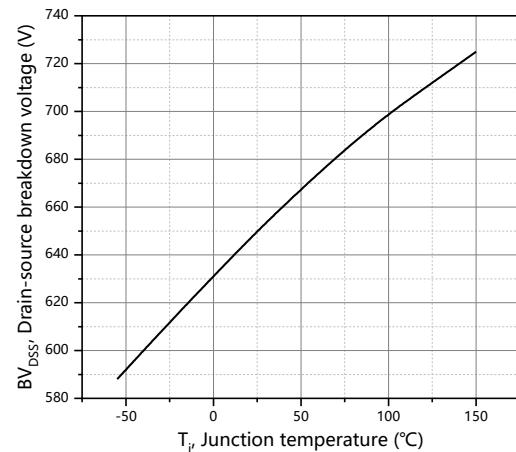


Figure 5. Drain-source breakdown voltage

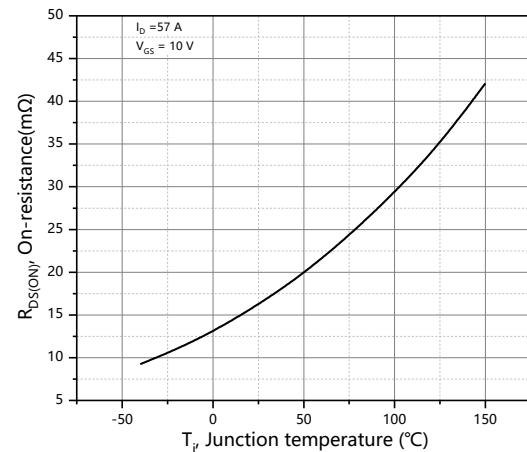
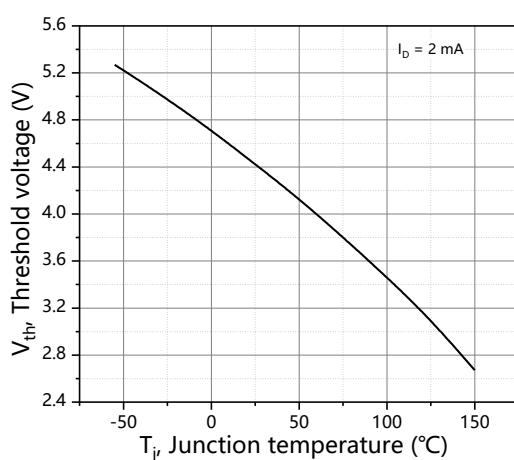
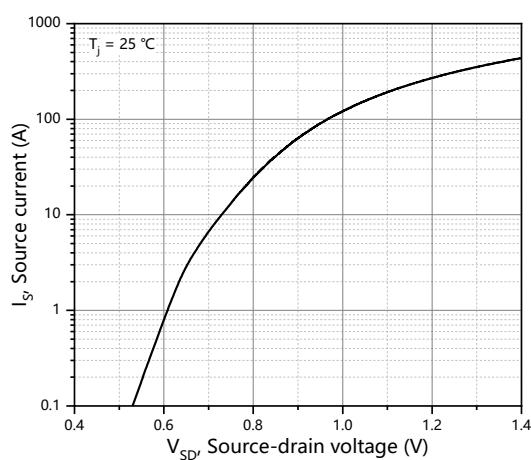
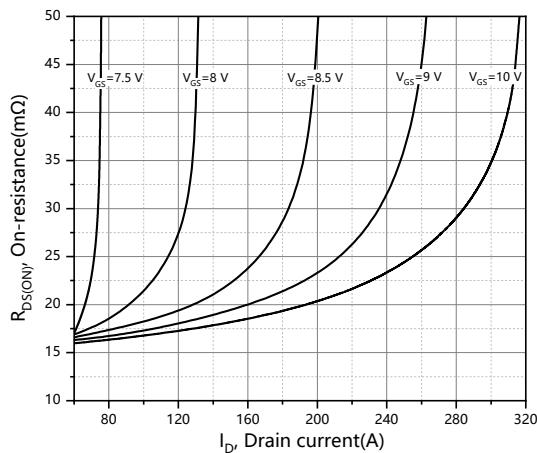
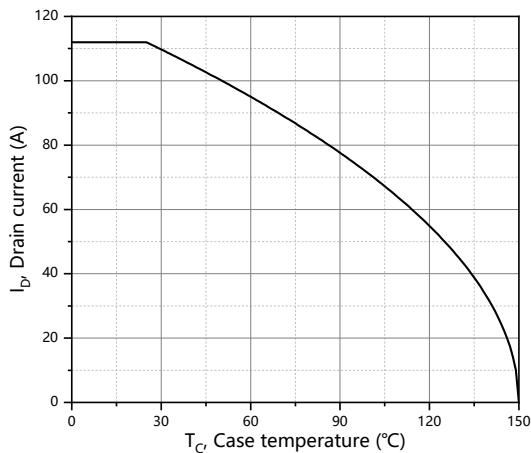
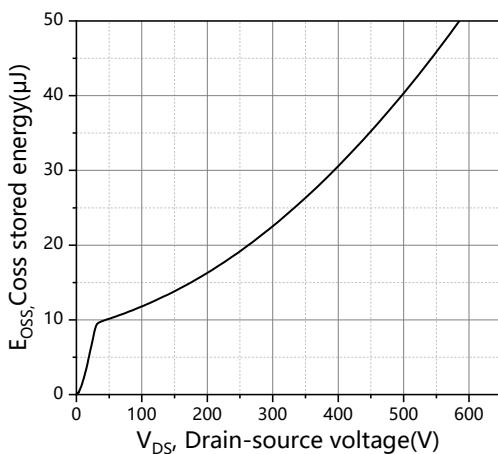
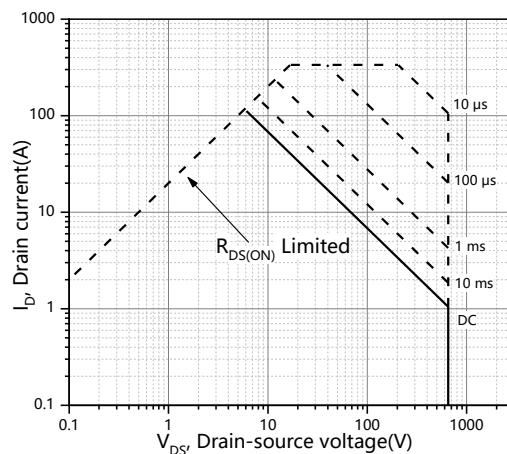


Figure 6. Drain-source on-state resistance


Figure 7. Threshold voltage

Figure 8. Forward characteristic of body diode

Figure 9. Drain-source on-state resistance

Figure 10. Drain current

Figure 11. Typ. Coss stored energy

Figure 12. Safe operation area $T_c=25^\circ\text{C}$

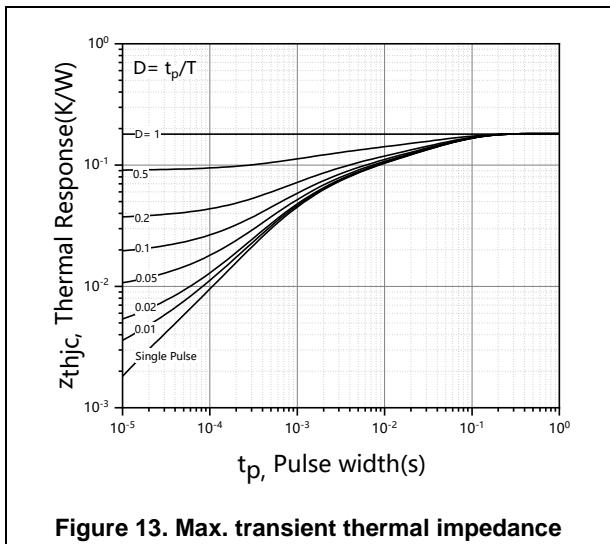


Figure 13. Max. transient thermal impedance

Test circuits and waveforms

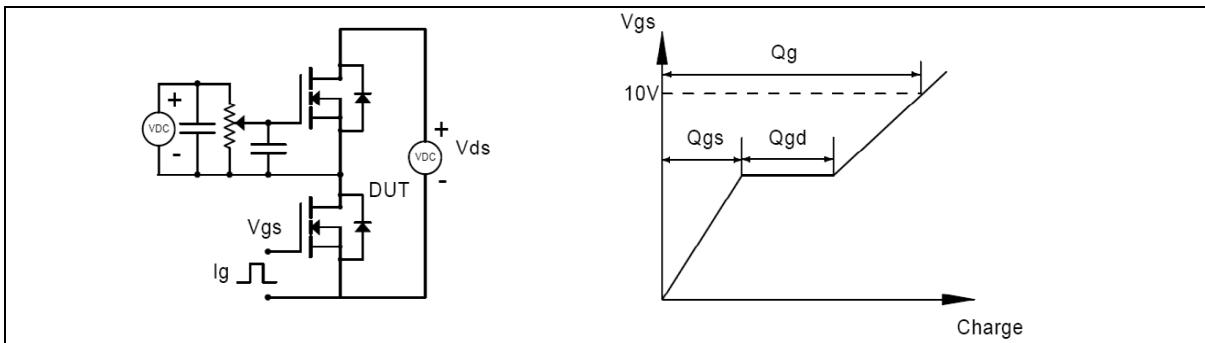


Figure 1. Gate charge test circuit & waveform

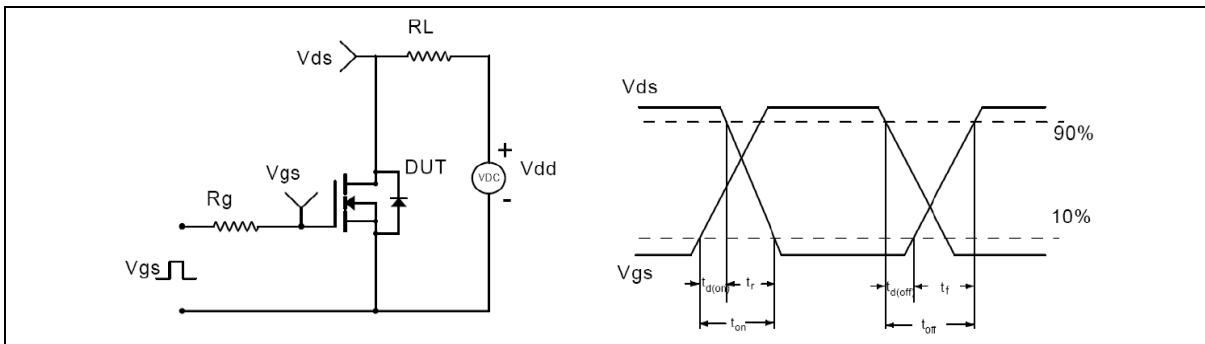


Figure 2. Switching time test circuit & waveforms

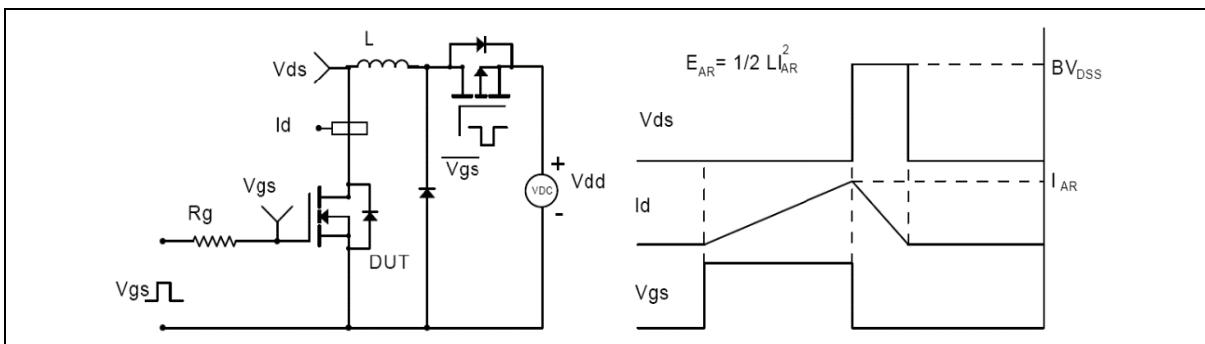


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

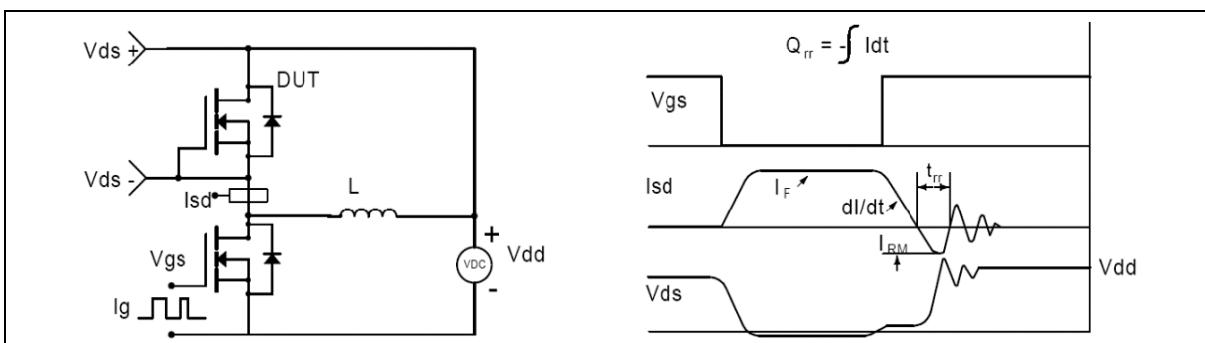
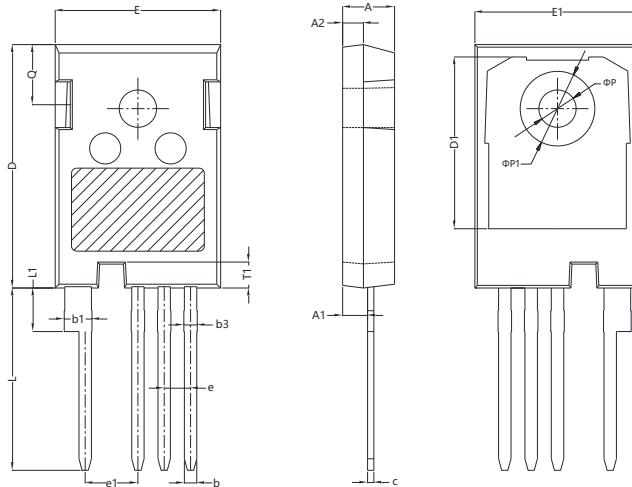


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.83	5.00	5.20
A1	2.21	2.41	2.61
A2	1.80	2.00	2.20
b	1.06	1.21	1.36
b1	2.33	2.63	2.93
b3	1.07	1.30	1.60
c	0.51	0.61	0.75
D	23.30	23.45	23.60
D1	16.25	16.55	16.85
E	15.74	15.94	16.14
E1	13.72	14.02	14.32
T1	2.35	2.50	2.65
e	2.54 BSC		
e1	5.08 BSC		
Q	5.49	5.79	6.09
L	17.27	17.57	17.87
L1	3.99	4.19	4.39
ΦP	3.40	3.60	3.80
ΦP1	7.19 REF		

Version: TO247-4L-P package outline dimension

Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO247-4L-P	30	11	330	6	1980

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R019H4T3ZF	TO247-4L	yes	yes	yes

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives (www.orientalsemi.com).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved /